

SEMICONDUCTOR DEVICE AND METHOD HAVING MULTIPLE SUBCOLLECTORS FORMED ON A COMMON WAFER

ABSTRACT OF THE DISCLOSURE

A semiconductor device and a method of fabricating a semiconductor device having multiple subcollectors which are formed in a common wafer, in order to provide multiple structures having different characteristic and frequency response are provided. The subcollectors may be provided using different doses or different material implants resulting in devices having different optimum unity current gain cutoff frequency (f_T) and breakdown voltage (BV_{CEO} and BV_{CBO}) on a common wafer.